



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE9104SH	Issued	13. May 2021
MA#	MA001949482		
Package	PG-DSO-20-88	Weight*	394.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.311	1.35	1.35	13458	13458
leadframe	inorganic material	phosphorus	7723-14-0	0.066	0.02		168	
	non noble metal	iron	7439-89-6	0.221	0.06		561	
	non noble metal	copper	7440-50-8	220.949	55.97	56.05	559840	560569
wire	non noble metal	copper	7440-50-8	1.287	0.33	0.33	3261	3261
encapsulation	organic material	carbon black	1333-86-4	0.477	0.12		1208	
	plastics	epoxy resin	-	18.601	4.71		47131	
	inorganic material	silicondioxide	60676-86-0	139.903	35.45	40.28	354486	402825
leadfinish	non noble metal	tin	7440-31-5	3.905	0.99	0.99	9895	9895
plating	noble metal	silver	7440-22-4	1.961	0.50	0.50	4969	4969
glue	plastics	epoxy resin	-	0.347	0.09		879	
	noble metal	silver	7440-22-4	1.635	0.41	0.50	4144	5023
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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